

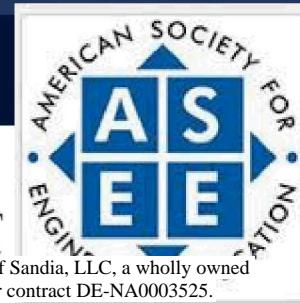


Surface Science Studies of GaN Substrates Subjected to Plasma-Assisted Atomic Layer Processes

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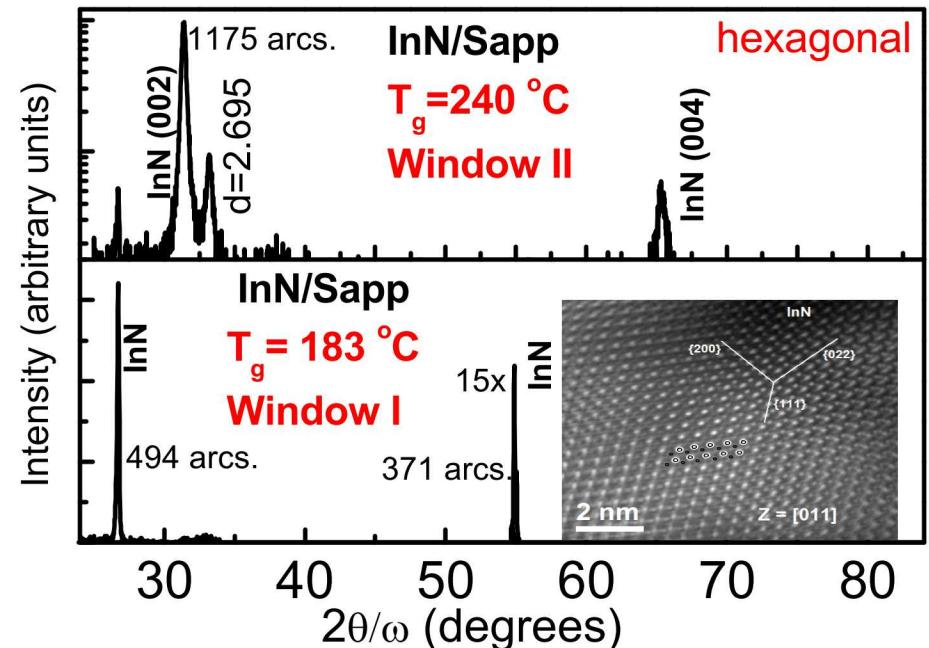
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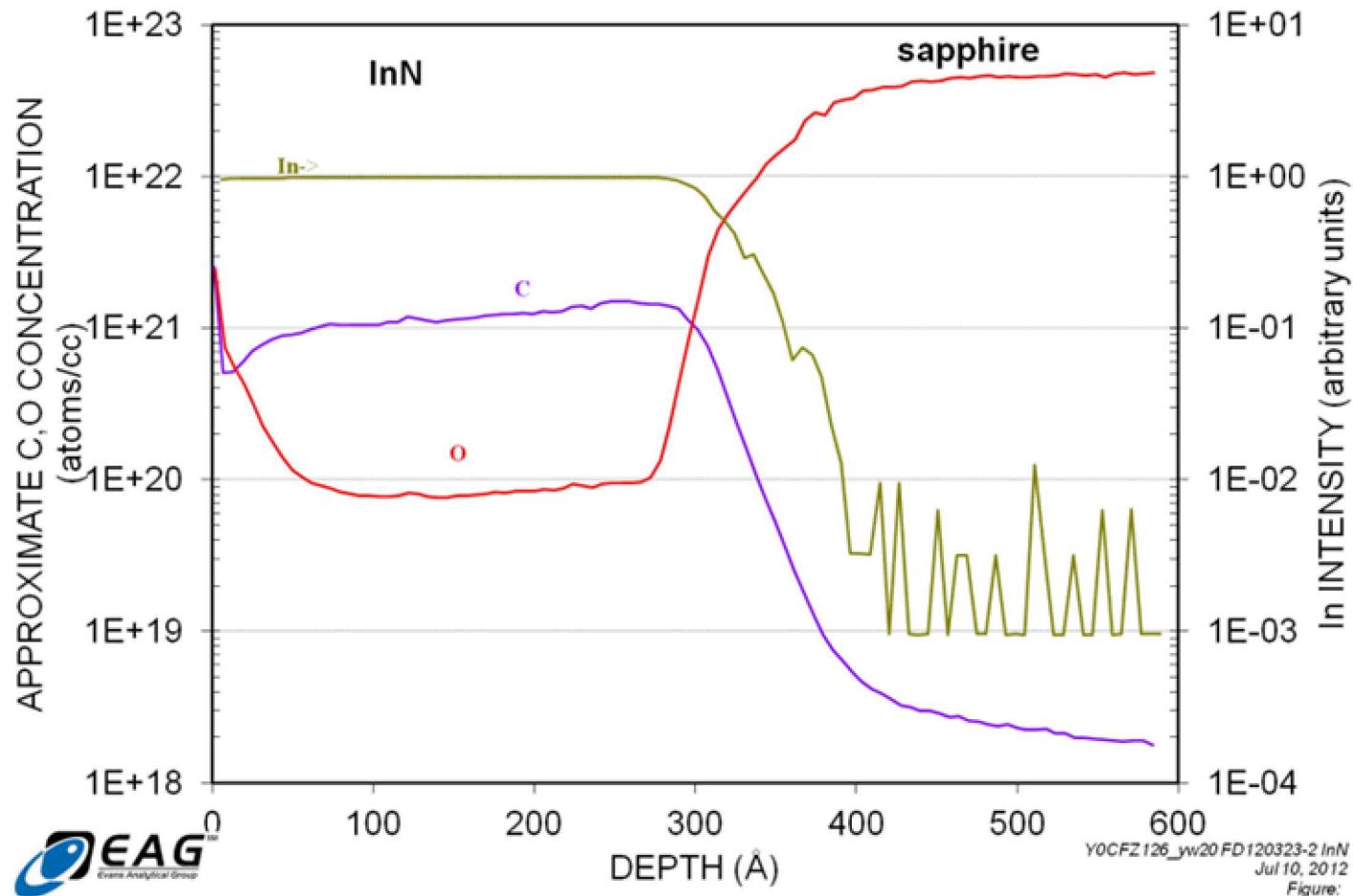
Motivation

Current prospects

- Plasma Assisted-ALE is one of the best methods to grow epitaxial materials at low temperature [1,2]
- We have reported ALEp of InN and two growth windows for cubic and hexagonal phases [1]
 - Two different phases of ALEp InN
 - For $T_g = 183^\circ\text{C}$: cubic phase (Window I)
 - For $T_g = 240^\circ\text{C}$: hexagonal phase (Window II)
- Still don't understand nucleation and growth mechanism
- Moving to GaN substrates for better lattice match



Contamination Issues



- plagued by 1000x too much carbon and oxygen by semiconductor purity standards

Experimental Procedure

Surface Preparation

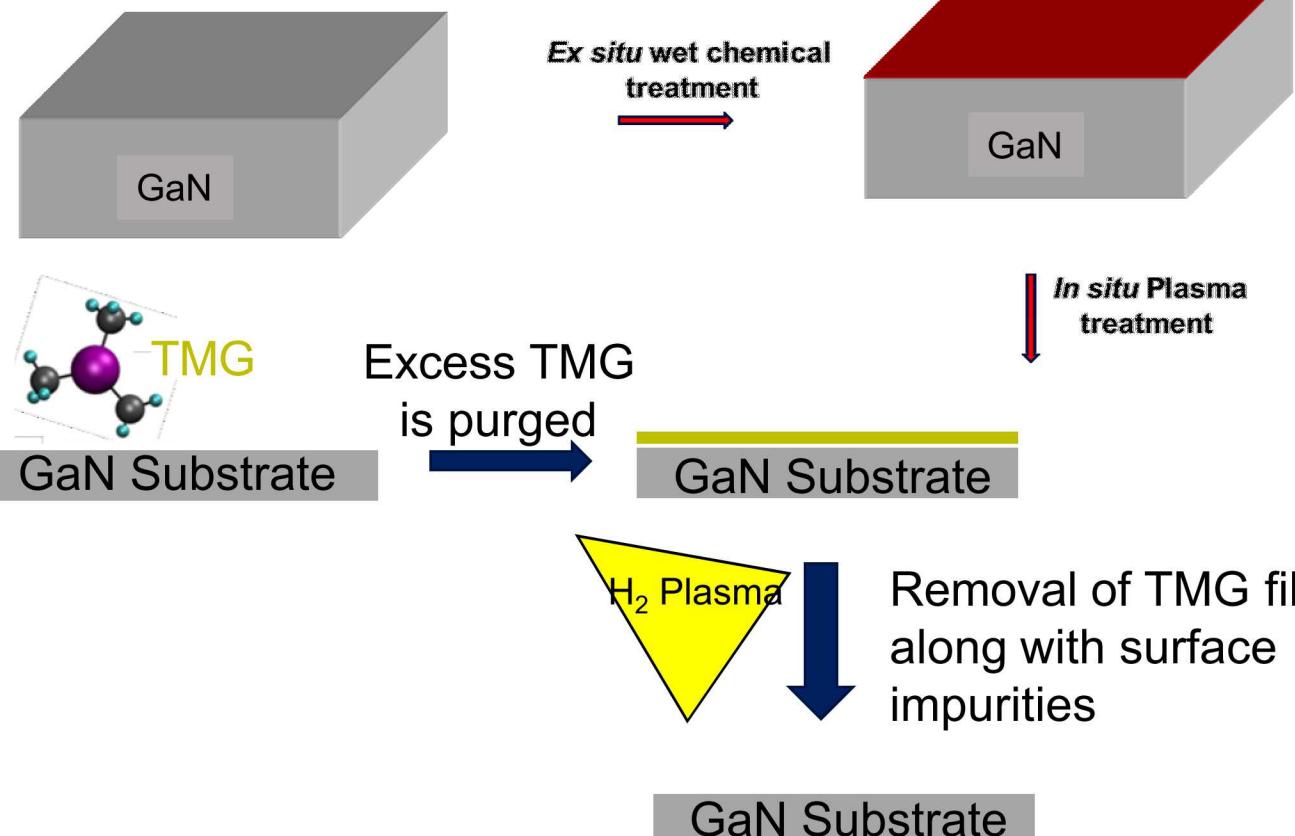
- Ex situ cleaning (wet chemical): Acetone & Isopropanol & DI, Then: UV/O₃ +HF
- In situ cleaning (Ga Flash Off Atomic Layer Process (GFO ALP), Plasma)

ALP Ga Flash Off

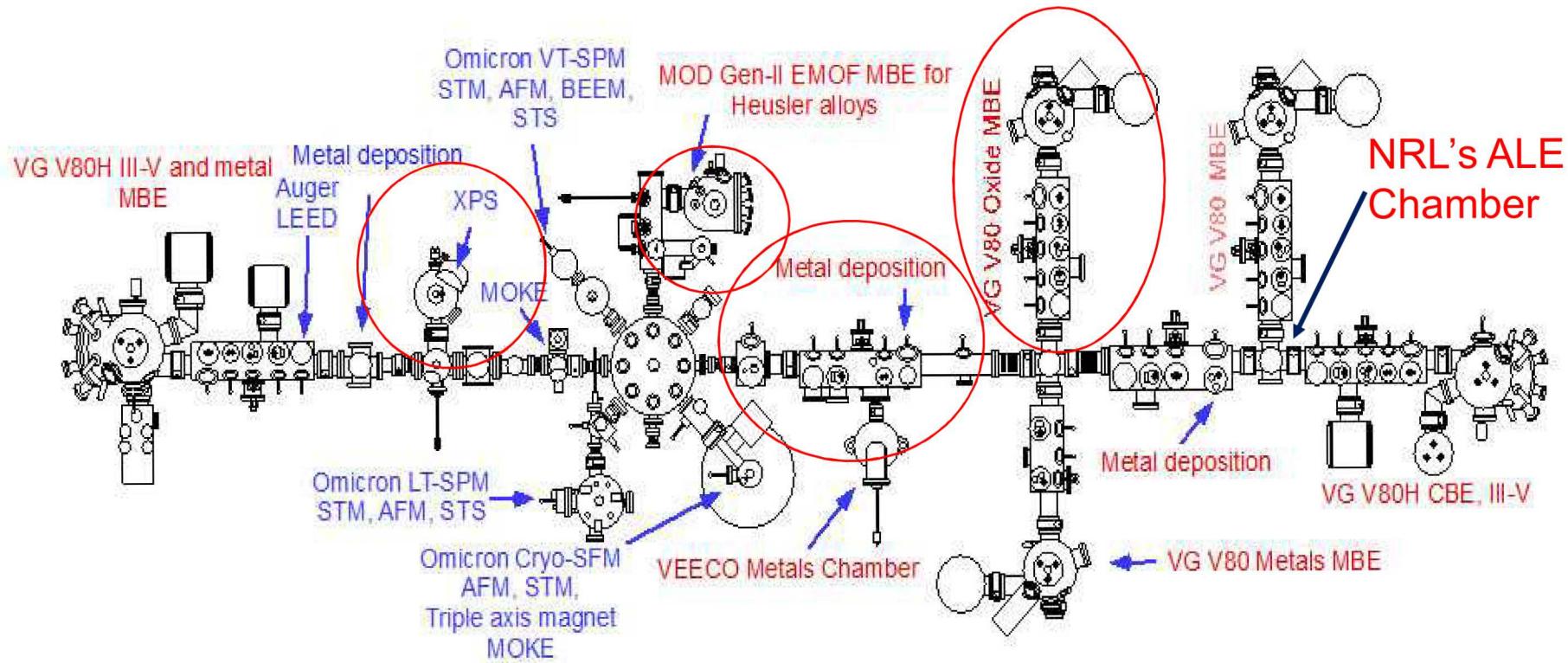
- TMG pulse : 60 ms
- Purge: 10 s
- Ar/H₂ plasma pulse : 21 s
- Purge : 19 s

Why surface cleaning?
Oxygen in lattice at surface,
adventitious carbon on surface

Process flow for epitaxial growth

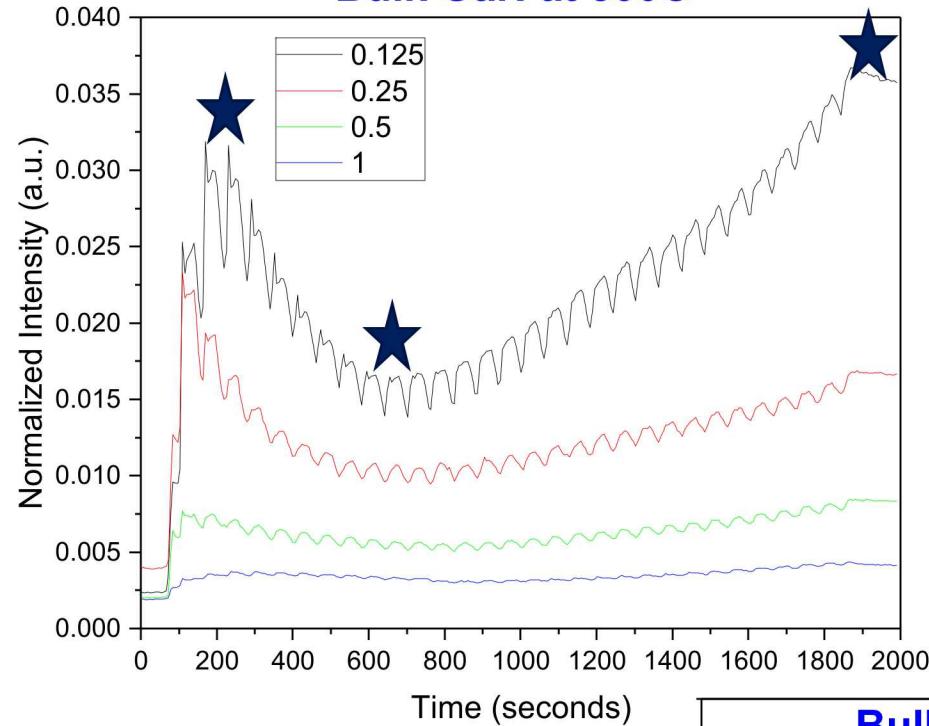


UCSB Chamber Set Up

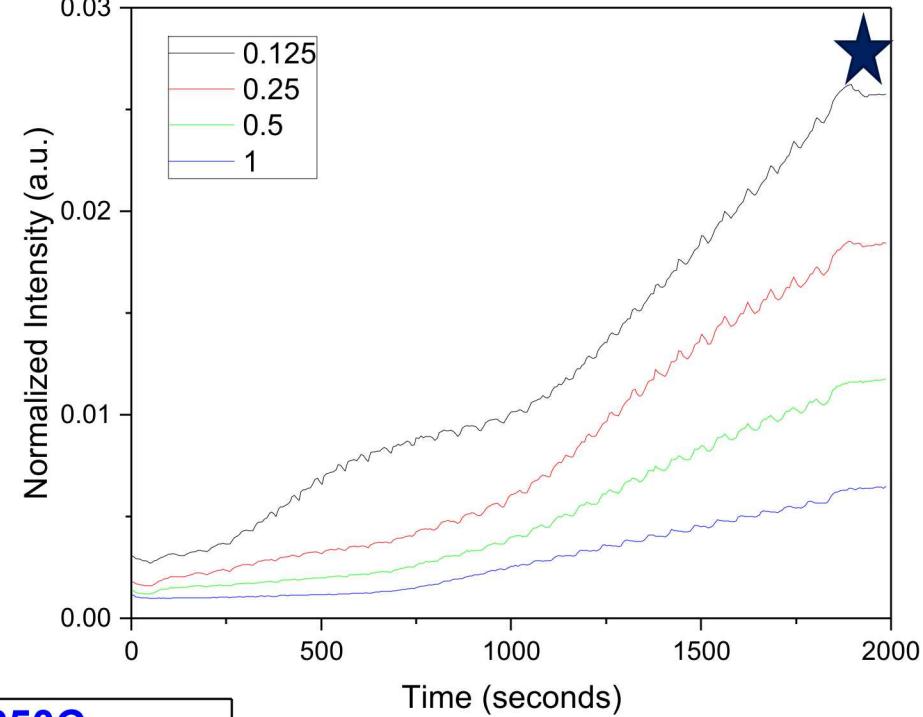


GISAXS of ALP Ga Flash Off at Different Temperatures

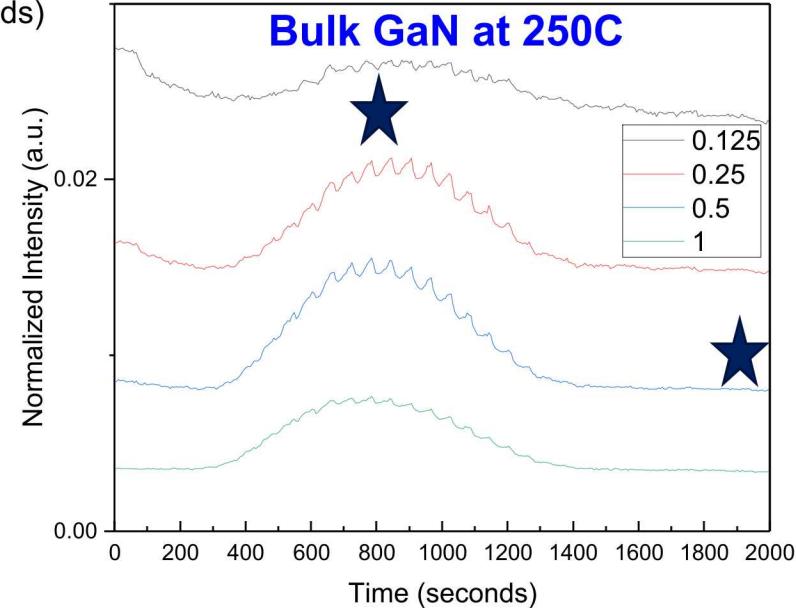
Bulk GaN at 500C



Bulk GaN at 400C



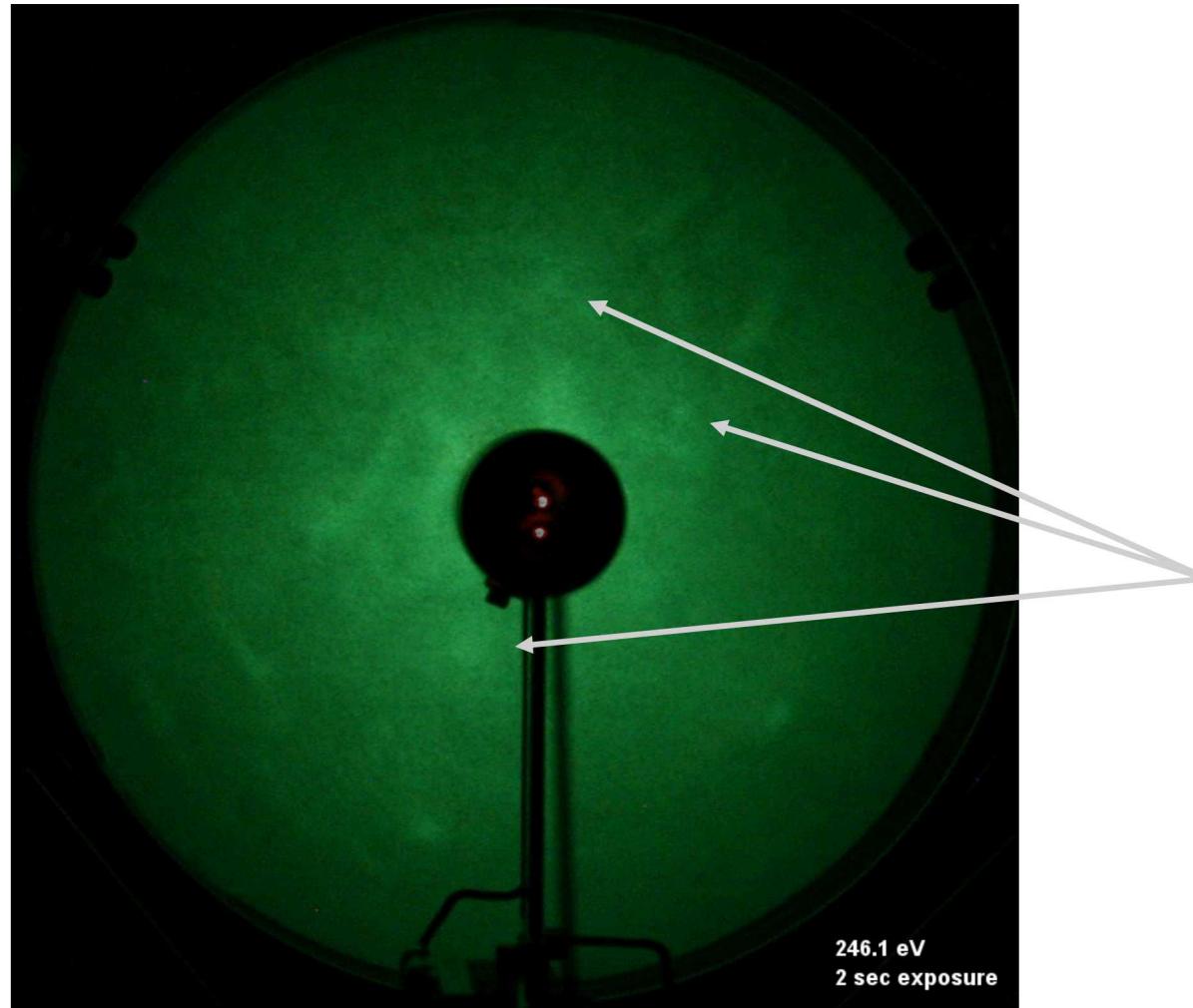
Bulk GaN at 250C



XPS Analysis

Temperature	GFO ALP Cycles	O/O ₀
250	12	0.956775
250	30	0.881354
400	30	1.083015
500	3	1.424906
500	10	0.71398
500	30	1.047371
500	10-Hydrogen only	0.784837
500	10-anneal	1.444746

LEED: As Received



Faint spots- in the shape of a hexagon.

LEED: After Ex-Situ Cleaning

Ex-Situ Cleaning:

5 min Swirl:

Acetone,

Isopropanol

DI water

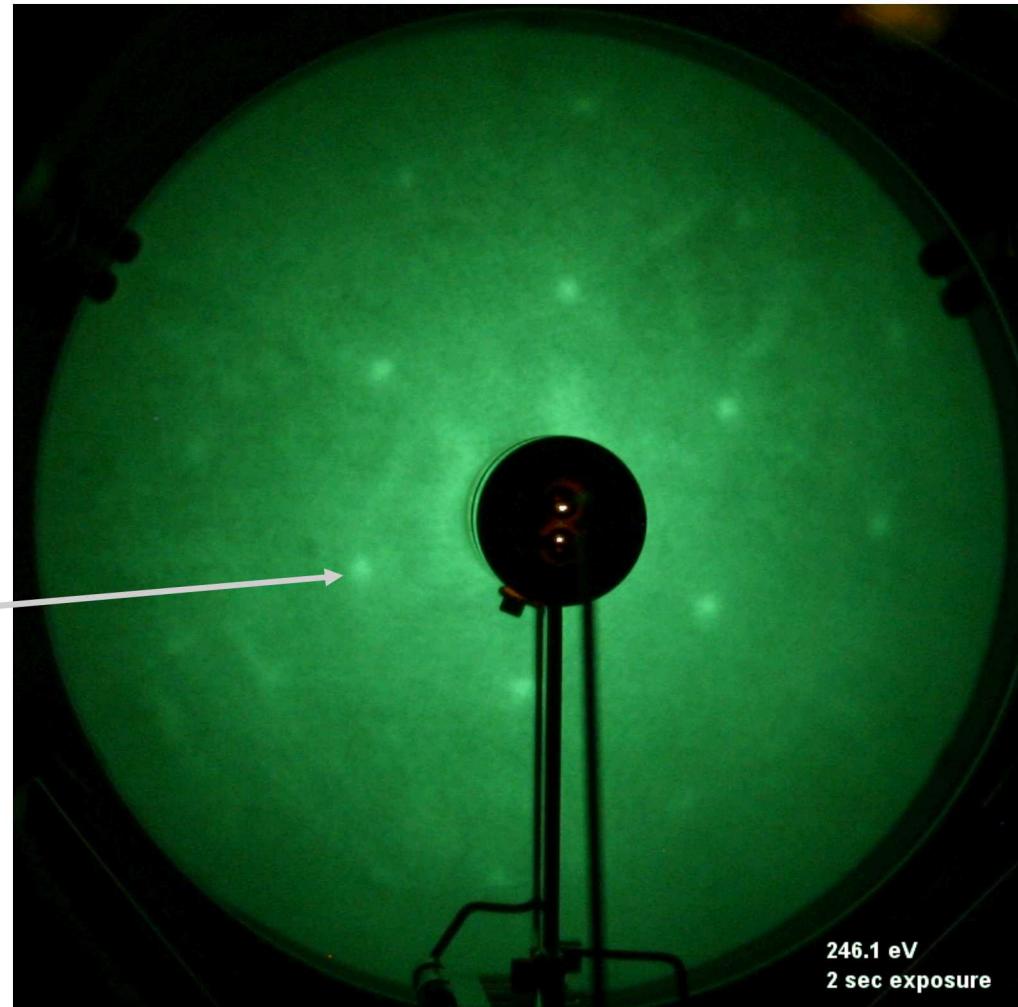
Dry with Nitrogen

Then:

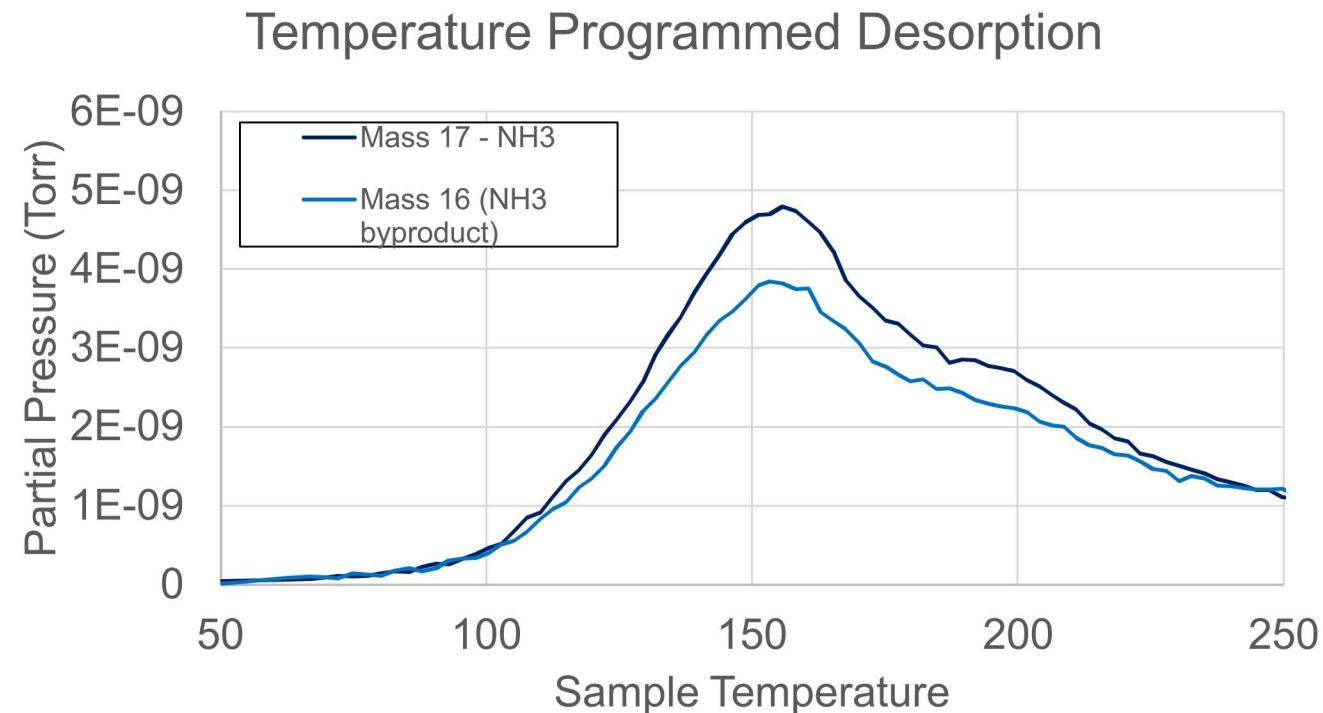
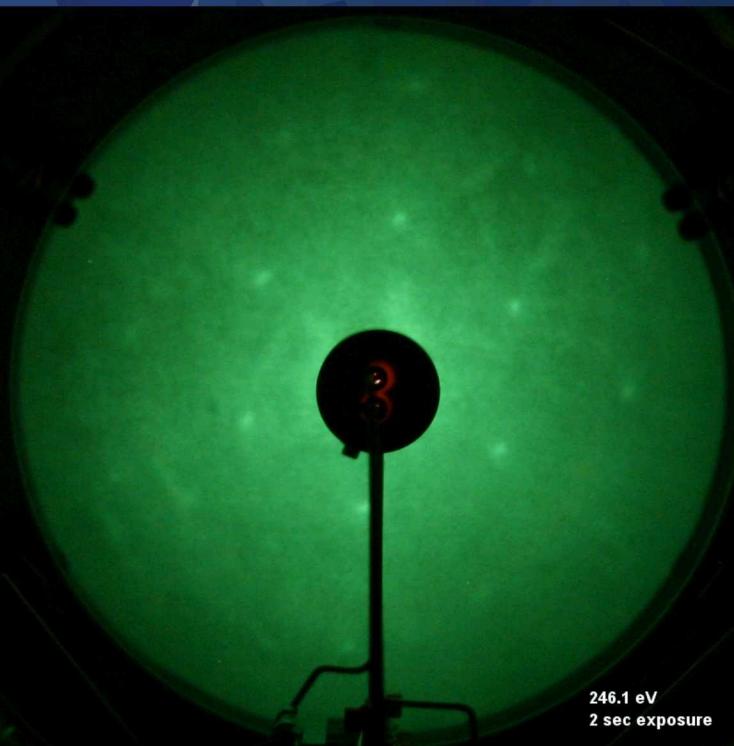
10 min UV/Ozone treatment

1 min concentrated HF etch

- Clear 6- fold symmetry.
- First order diffraction spots
- Well-ordered & un-
reconstructed surface

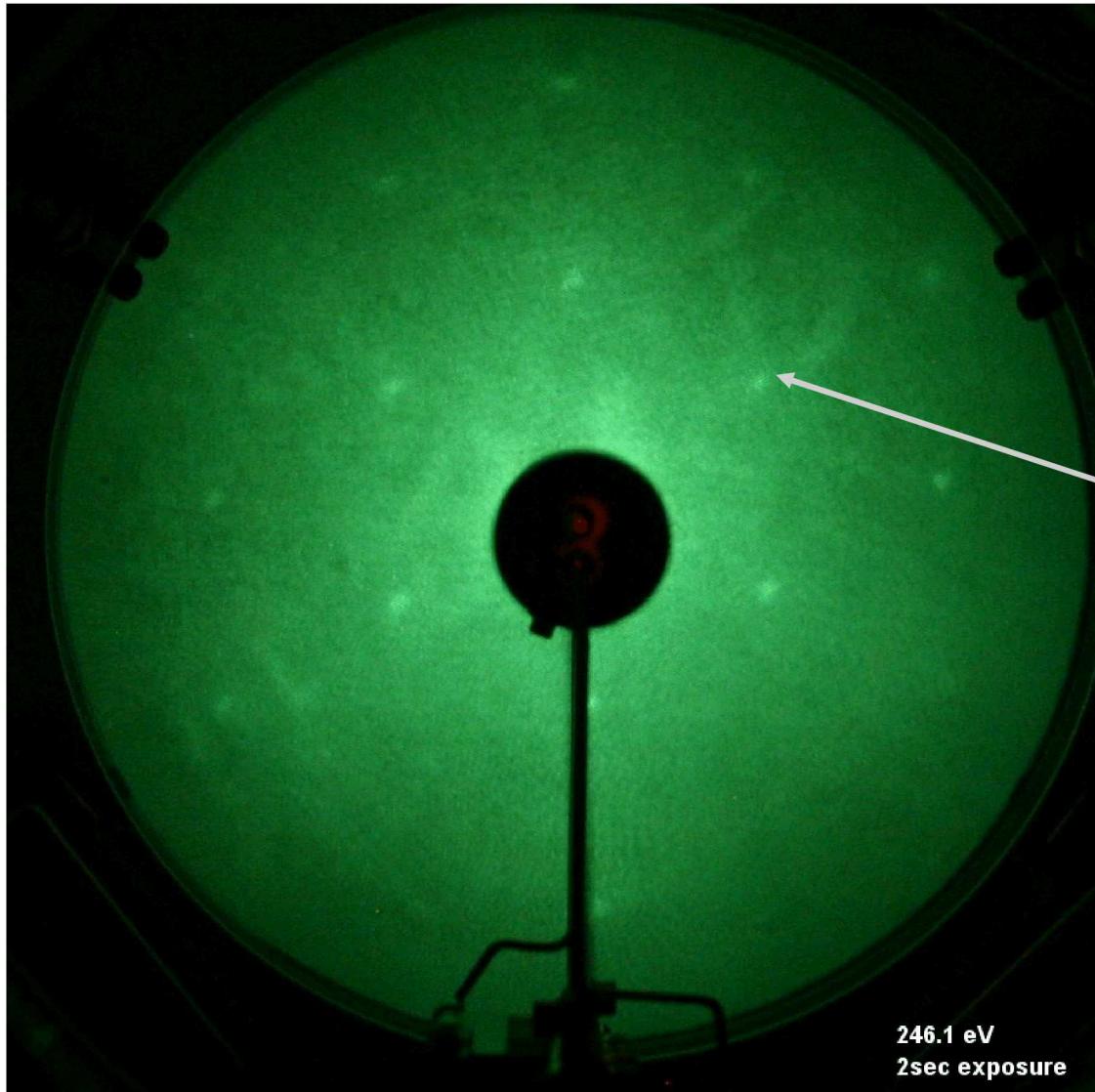


LEED & TPD of Ex-Situ Cleaned GaN



NH₃ is released from the surface as the substrate is heated

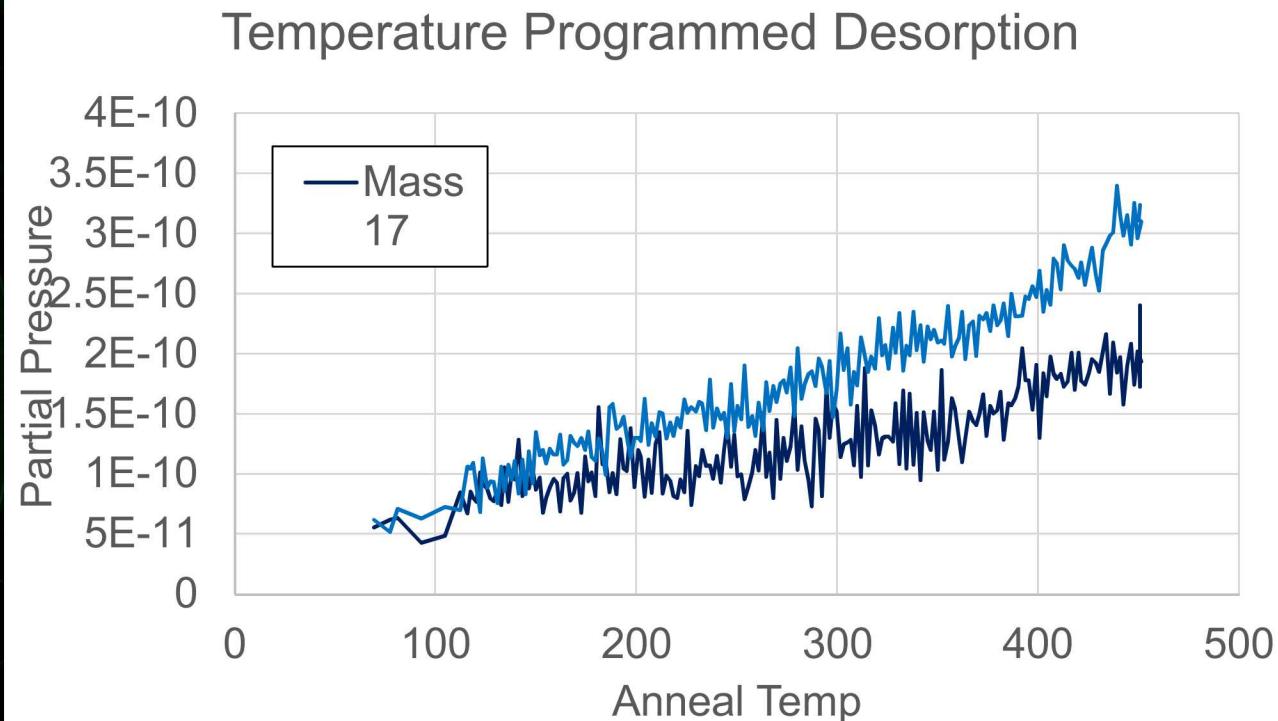
LEED on GFO ALP GaN



Ex-situ Cleaned followed by
GFO ALP in commercial tool at
500C for 10 cycles.

- Clear 6- fold symmetry.
- First order diffraction spots
- Well-ordered & un-
reconstructed surface
- Same as Ex-situ surface,

LEED & TPD of GFO ALP Cleaned GaN



No NH_3 is released from the surface as the substrate is heated, most likely meaning that all the N has been tied up through the GFO ALP.

Summary

- **GFO ALP at 500C for 10 cycles and with hydrogen only for 10 cycles, both show a ~25% reduction in Oxygen on the surface**
- ***Ex-situ GaN surface and GFO ALP GaN surface are both well ordered and unreconstructed***
- ***Ex-situ GaN surface when heated in TPD experiments evolves NH₃ from the surface, suggesting that the Nitrogen is not ordered on the surface***
- ***GFO ALP seems to make the GaN surface air stable***
- **In-situ & Ex-situ techniques are capable of developing the optimum Low-Temperature ALP**

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